



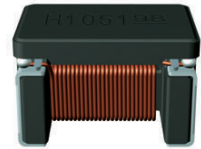
Data and signal line chokes

ACT45B common-mode chokes for CAN bus systems, EIA 1812
51 ... 100 μ H, 150 ... 200 mA

Series/Type: ACT45B
Date: November 2012

SMD

Rated voltage 50 V DC
Rated inductance 51 ... 100 μ H
Rated current 150 ... 200 mA



Construction

- Current-compensated double choke
- Ferrite I core
- Winding: enamel copper wire
- Winding welded to terminals

Features

- Operating temperature range: $-40 \dots +150 \text{ }^\circ\text{C}$
- Qualified to AEC-Q200
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- RoHS-compatible

Function

- Suppression of assymetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly.

Applications

- Automotive CAN bus systems

Terminals

Tinned terminals:

- Base material CuSn8
- Dip-plating Sn
- Lead-free tinned

Marking

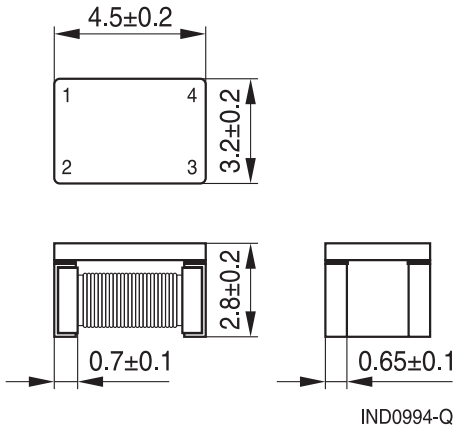
- Marking on component: L value ("G" = 51 μ H, "H" = 100 μ H), date of manufacture (YWWD), two last digits of production order ()

Delivery mode and packing unit

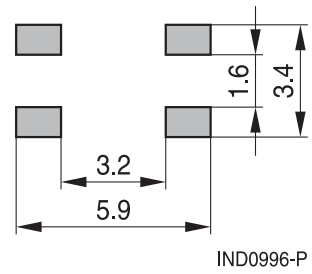
- 12-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 2500 pcs./reel

SMD

Dimensional drawing and pin configuration

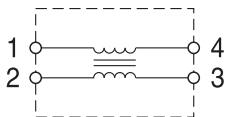


Layout recommendation



Dimensions in mm

Circuit diagram

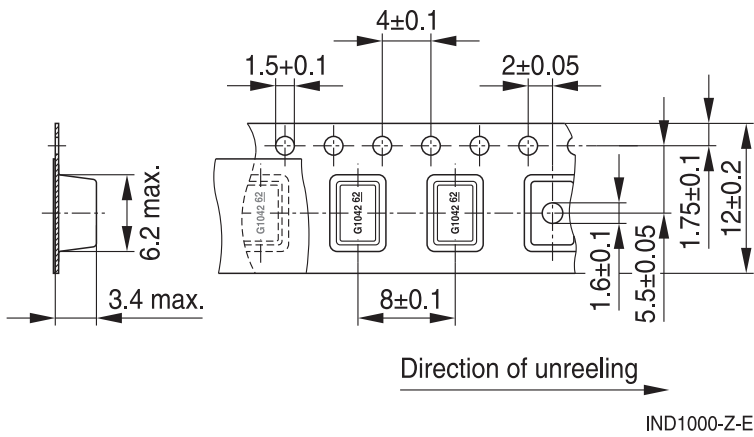


- No polarity

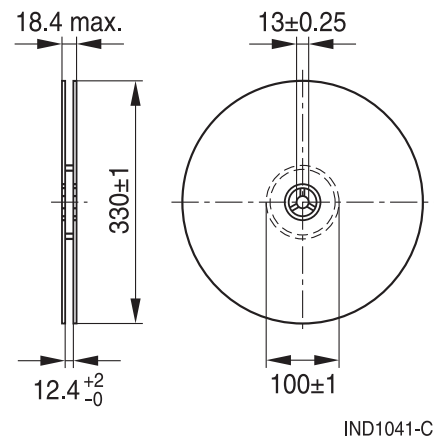
IND0995-W

Taping and packing

Blister tape



Reel



Dimensions in mm

Technical data and measuring conditions

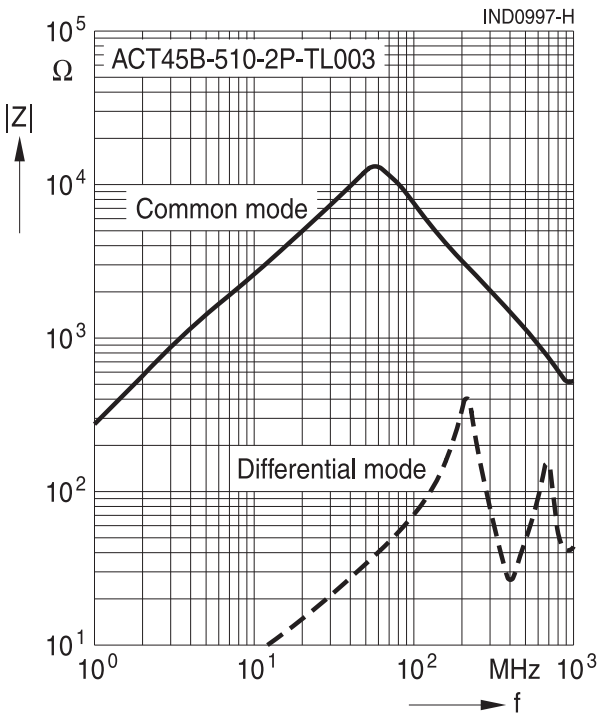
Rated voltage V_R	50 V DC
Max. component temperature	+150 °C
Rated current I_R	Referred to 50 Hz and +20 °C
Rated inductance L_R	Measured with Agilent 4284A at 100 kHz, 100 mV, +20 °C Inductance is specified in common-mode
Inductance tolerance	-30/+50% at +20 °C
Stray inductance $L_{\text{stray,typ}}$	Measured with Agilent 4284A at 100 kHz, 100 mV, +20 °C, typical values
DC resistance R_{max}	Measured at +20 °C, specified per winding
Insulation resistance (min)	10 M Ω , measured at 50 V DC
Rated impedance Z_{min}	Measured at +20 °C, 10 MHz, 100 mV in common-mode
Rated impedance Z_{typ}	Measured at +20 °C, 10 MHz, 100 mV in common-mode
Solderability	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 \pm 5) °C, (3 \pm 0.3) s Wetting of soldering area \geq 90% (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s as referenced in JEDEC J-STD 020D
Climatic category	40/150/56 (to IEC 60068-1)
Storage conditions (packaged)	-25 °C ... +40 °C, \leq 75% RH
Weight	Approx. 0.14 g

Characteristics and ordering codes

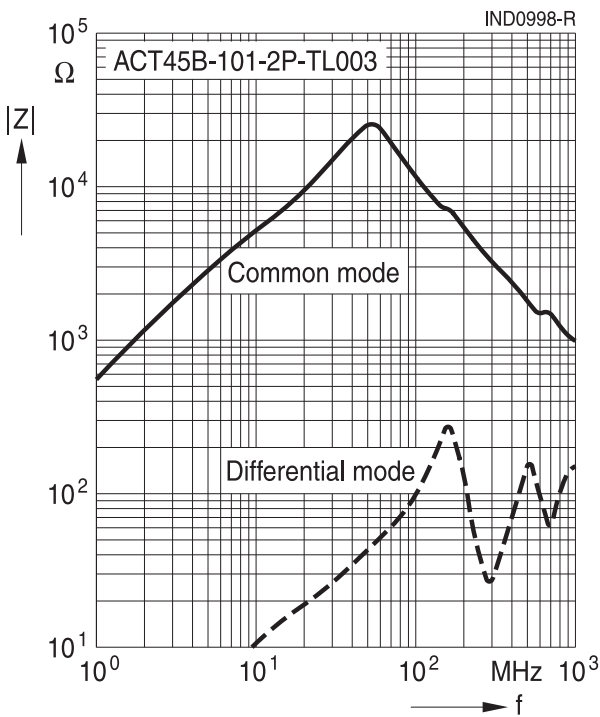
L_R μH	$L_{\text{stray,typ}}$ μH	I_R mA	R_{max} Ω	Z_{min} Ω	Z_{typ} Ω	Internal code	Ordering code
51	0.15	200	1.0	1000	2800	B82787C0513H002	ACT45B-510-2P-TL003
100	0.20	150	2.0	2000	5800	B82787C0104H002	ACT45B-101-2P-TL003

Impedance versus frequency

ACT45B-510-2P-TL003



ACT45B-101-2P-TL003



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.
5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order.

We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available. The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

6. Unless otherwise agreed in individual contracts, **all orders are subject to the current version of the “General Terms of Delivery for Products and Services in the Electrical Industry” published by the German Electrical and Electronics Industry Association (ZVEI)**.
7. The trade names EPCOS, BAOKE, Alu-X, CeraDiode, CeraLink, CSMP, CSSP, CTVS, DeltaCap, DigiSiMic, DSSP, FilterCap, FormFit, MiniBlue, MiniCell, MKD, MKK, MLSC, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SIP5D, SIP5K, ThermoFuse, WindCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at www.epcos.com/trademarks.